

74LVQ245 Low Voltage Octal Bidirectional Transceiver with 3-STATE Outputs

General Description

The LVQ245 contains eight non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus-oriented applications. Current sinking capability is 12 mA at both the A and B ports. The Transmit/Receive (T/R) input determines the direction of data flow through the bidirectional transceiver. Transmit (active-HIGH) enables data from A ports to B ports; Receive (active-LOW) enables data from B ports to A ports. The Output Enable input, when HIGH, disables both A and B ports by placing them in a HIGH Z condition.

Features

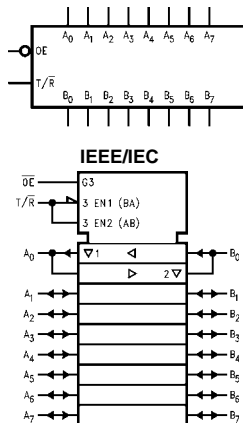
- Ideal for low power/low noise 3.3V applications
- Implements patented EMI reduction circuitry
- Available in SOIC JEDEC, SOIC EIAJ and QSOP packages
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Improved latch-up immunity
- Guaranteed incident wave switching into 75Ω
- 4 kV minimum ESD immunity

Ordering Code

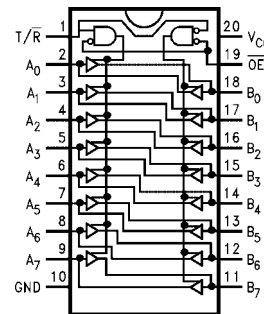
| Order Number | Package Number | Package Description |
|--------------|----------------|--|
| 74LVQ245SC | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 74LVQ245SJ | M20D | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LVQ245QSC | MQA20 | 20-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150" Wide |

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Logic Symbols



Connection Diagram



Truth Table

| Inputs | | Outputs |
|--------|-----|---------------------|
| OE | T/R | |
| L | L | Bus B Data to Bus A |
| L | H | Bus A Data to Bus B |
| H | X | HIGH-Z State |

H = HIGH Voltage Level L = LOW Voltage Level X = Immaterial

Pin Descriptions

| Pin Names | Description |
|--------------------------------|----------------------------------|
| OE | Output Enable Inputs |
| T/R | Transmit/Receive Input |
| A ₀ -A ₇ | Side A Inputs or 3-STATE Outputs |
| B ₀ -B ₇ | Side B Inputs or 3-STATE Outputs |

Absolute Maximum Ratings (Note 1)

| | |
|---|--------------------------|
| Supply Voltage (V_{CC}) | -0.5V to +7.0V |
| DC Input Diode Current (I_{IK}) | |
| $V_I = -0.5V$ | -20 mA |
| $V_I = V_{CC} + 0.5V$ | +20 mA |
| DC Input Voltage (V_I) | -0.5V to $V_{CC} + 0.5V$ |
| DC Output Diode Current (I_{OK}) | |
| $V_O = -0.5V$ | -20 mA |
| $V_O = V_{CC} + 0.5V$ | +20 mA |
| DC Output Voltage (V_O) | -0.5V to $V_{CC} + 0.5V$ |
| DC Output Source or Sink Current (I_O) | ± 50 mA |
| DC V_{CC} or Ground Current (I_{CC} or I_{GND}) | ± 400 mA |
| Storage Temperature (T_{STG}) | -65°C to +150°C |
| DC Latch-Up Source or Sink Current | ± 300 mA |

Recommended Operating Conditions (Note 2)

| | |
|---|----------------|
| Supply Voltage (V_{CC}) | 2.0V to 3.6V |
| Input Voltage (V_I) | 0V to V_{CC} |
| Output Voltage (V_O) | 0V to V_{CC} |
| Operating Temperature (T_A) | -40°C to +85°C |
| Minimum Input Edge Rate ($\Delta V/\Delta t$) | |
| V_{IN} from 0.8V to 2.0V | |
| V_{CC} @ 3.0V | 125 mV/ns |

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 2: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

| Symbol | Parameter | V_{CC} (V) | $T_A = +25^\circ\text{C}$ | | $T_A = -40^\circ\text{C to } +85^\circ\text{C}$ | | Units | Conditions |
|-----------|--|-----------------|---------------------------|-------------------|---|---------------|---|------------|
| | | | Typ | Guaranteed Limits | | | | |
| V_{IH} | Minimum High Level Input Voltage | 3.0 | 1.5 | 2.0 | 2.0 | V | $V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$ | |
| V_{IL} | Maximum Low Level Input Voltage | 3.0 | 1.5 | 0.8 | 0.8 | V | $V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$ | |
| V_{OH} | Minimum High Level Output Voltage | 3.0 | 2.99 | 2.9 | 2.9 | V | $I_{OUT} = -50 \mu\text{A}$ | |
| | | 3.0 | | 2.58 | 2.48 | V | $V_{IN} = V_{IL}$ or V_{IH} (Note 3) $I_{OH} = -12 \text{ mA}$ | |
| V_{OL} | Maximum Low Level Output Voltage | 3.0 | 0.002 | 0.1 | 0.1 | V | $I_{OUT} = 50 \mu\text{A}$ | |
| | | 3.0 | | 0.36 | 0.44 | V | $V_{IN} = V_{IL}$ or V_{IH} (Note 3) $I_{OL} = +12 \text{ mA}$ | |
| I_{IN} | Maximum Input Leakage Current | 3.6 | | ± 0.1 | ± 1.0 | μA | $V_I = V_{CC}, \text{ GND}$ | |
| I_{OLD} | Minimum Dynamic Output Current (Note 4) | 3.6 | | | 36 | mA | $V_{OLD} = 0.8V \text{ Max}$ (Note 5) | |
| I_{OHD} | Maximum Dynamic Output Current (Note 4) | 3.6 | | | -25 | mA | $V_{OHD} = 2.0V \text{ Min}$ (Note 5) | |
| I_{CC} | Maximum Quiescent Supply Current | 3.6 | | 4.0 | 40.0 | μA | $V_{IN} = V_{CC}$ or GND | |
| I_{OZT} | Maximum I/O Leakage Current | 3.6 | | ± 0.3 | ± 3.0 | μA | $V_I (\overline{\text{OE}}) = V_{IL}, V_{IH}$ $V_I = V_{CC}, \text{ GND}$ $V_O = V_{CC}, \text{ GND}$ | |
| V_{OLP} | Quiet Output Maximum Dynamic V_{OL} | 3.3 | 0.5 | 0.8 | | V | (Note 6)(Note 7) | |
| V_{OLV} | Quiet Output Minimum Dynamic V_{OL} | 3.3 | -0.5 | -0.8 | | V | (Note 6)(Note 7) | |
| V_{IHD} | Maximum High Level Dynamic Input Voltage | 3.3 | 1.6 | 2.0 | | V | (Note 6)(Note 8) | |
| V_{ILD} | Maximum Low Level Dynamic Input Voltage | 3.3 | 1.7 | 0.8 | | V | (Note 6)(Note 8) | |

Note 3: All outputs loaded; thresholds on input associated with output under test.

Note 4: Maximum test duration 2.0 ms, one output loaded at a time.

Note 5: Incident wave switching on transmission lines with impedances as low as 75 Ω for commercial temperature range is guaranteed for 74LVQ.

Note 6: Worst case package.

Note 7: Max number of outputs defined as (n). Data inputs are driven 0V to 3.3V; one output at GND.

Note 8: Max number of Data Inputs (n) switching. (n - 1) inputs switching 0V to 3.3V. Input-under-test switching: 3.3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}), $f = 1 \text{ MHz}$.

AC Electrical Characteristics

| Symbol | Parameter | V _{CC} (V) | T _A = +25°C C _L = 50 pF | | | T _A = -40°C to +85°C C _L = 50 pF | | Units |
|-------------------|-----------------------------------|------------------------|--|------|------|---|------|-------|
| | | | Min | Typ | Max | Min | Max | |
| t _{PHL} | Propagation Delay | 2.7 | 2.0 | 9.0 | 14.0 | 2.0 | 15.0 | ns |
| t _{PLH} | | 3.3 ± 0.3 | 2.0 | 7.5 | 10.0 | 2.0 | 10.5 | |
| t _{PZL} | Output Enable Time | 2.7 | 3.0 | 10.2 | 18.3 | 3.0 | 19.0 | ns |
| t _{PZH} | | 3.3 ± 0.3 | 3.0 | 8.5 | 13.0 | 3.0 | 13.5 | |
| t _{PHZ} | Output Disable Time | 2.7 | 1.0 | 10.2 | 20.4 | 1.0 | 21.0 | ns |
| t _{PLZ} | | 3.3 ± 0.3 | 1.0 | 8.5 | 14.5 | 1.0 | 15.0 | |
| t _{OSSL} | Output to Output Skew (Note 9) | 2.7 | | 1.0 | 1.5 | | 1.5 | ns |
| t _{OSLH} | | 3.3 ± 0.3 | | 1.0 | 1.5 | | 1.5 | |

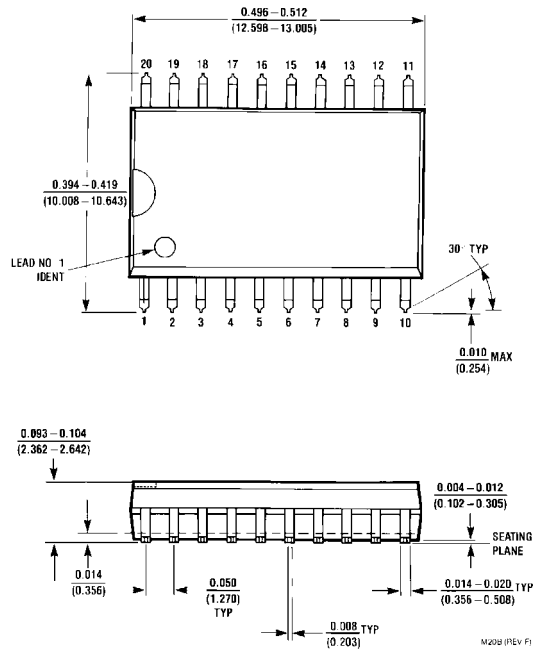
Note 9: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSSL}) or LOW-to-HIGH (t_{OSLH}). Parameter guaranteed by design.

Capacitance

| Symbol | Parameter | Typ | Units | Conditions |
|---------------------------|-------------------------------|-----|-------|------------------------|
| C _{IN} | Input Capacitance | 4.5 | pF | V _{CC} = Open |
| C _{I/O} | Input/Output Capacitance | 15 | pF | V _{CC} = 3.3V |
| C _{PD} (Note 10) | Power Dissipation Capacitance | 67 | pF | V _{CC} = 3.3V |

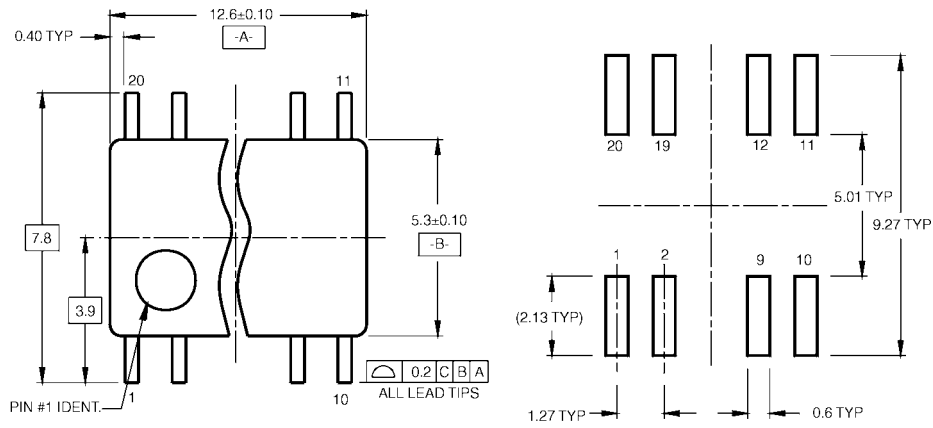
Note 10: C_{PD} is measured at 10 MHz.

Physical Dimensions inches (millimeters) unless otherwise noted

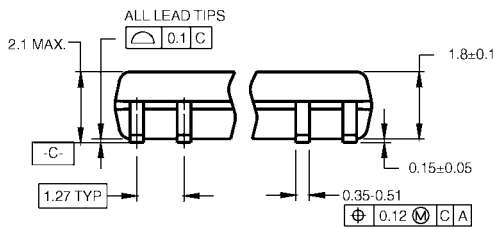


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B**

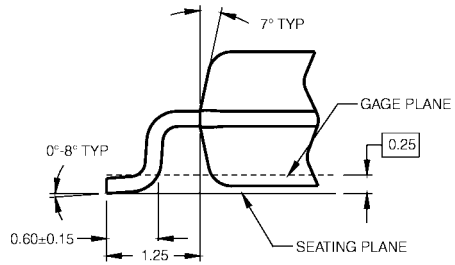
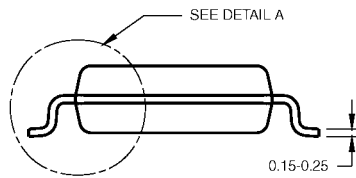
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



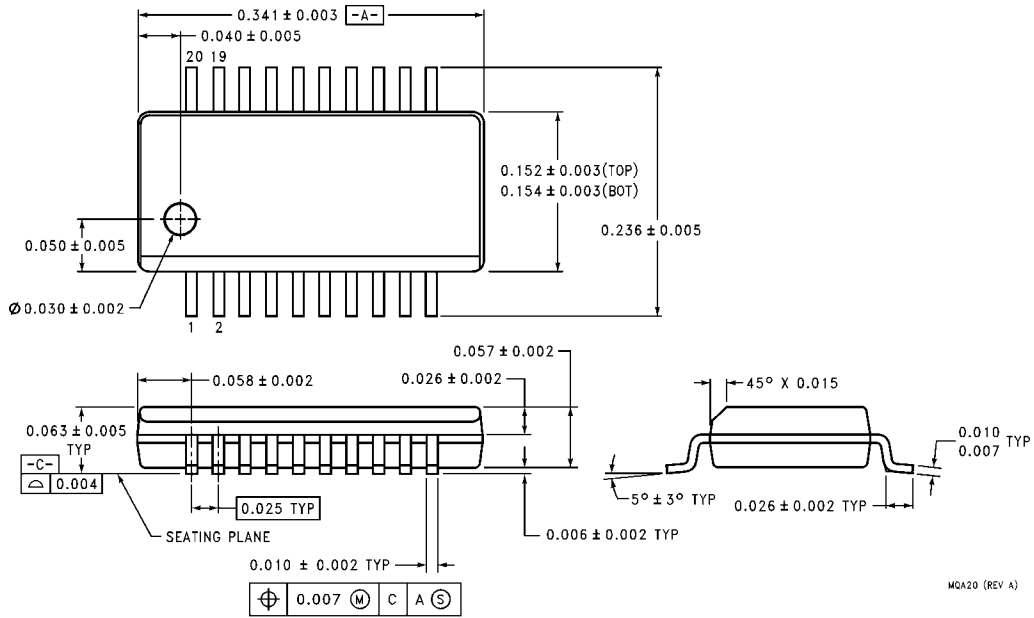
DETAIL A

- NOTES:
- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 - B. DIMENSIONS ARE IN MILLIMETERS.
 - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



**20-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150" Wide
Package Number MQA20**

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com